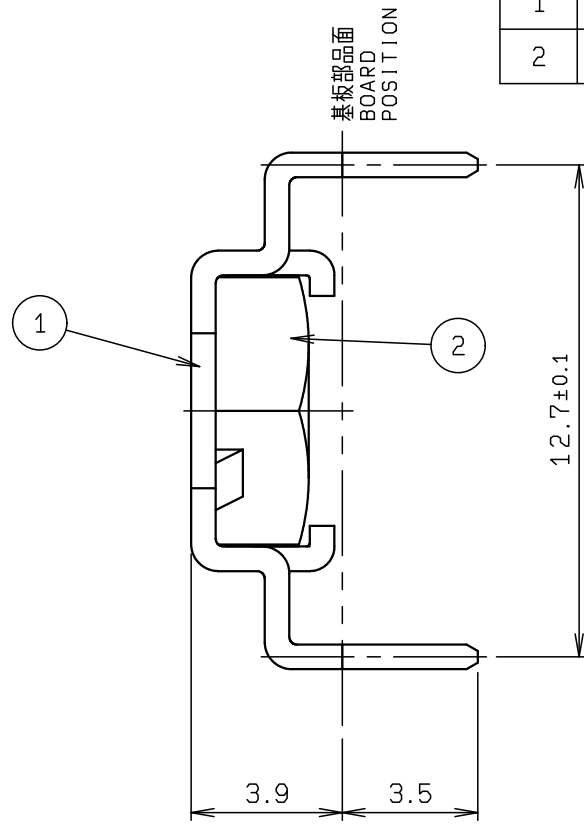
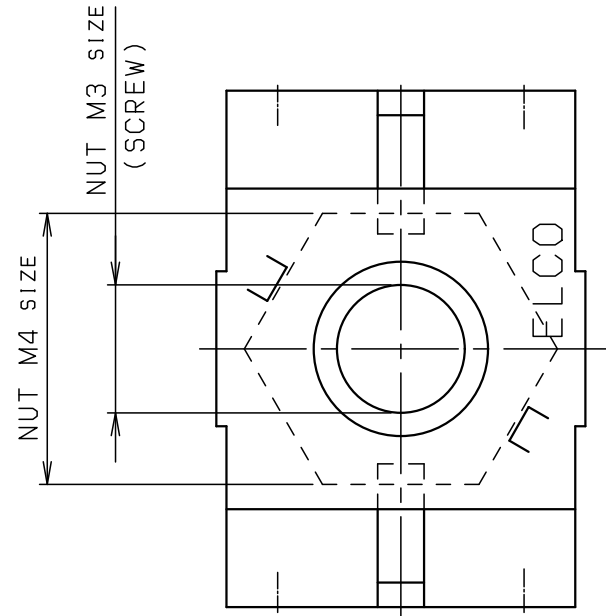
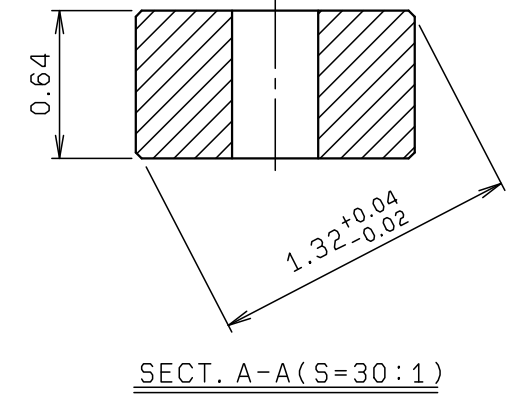
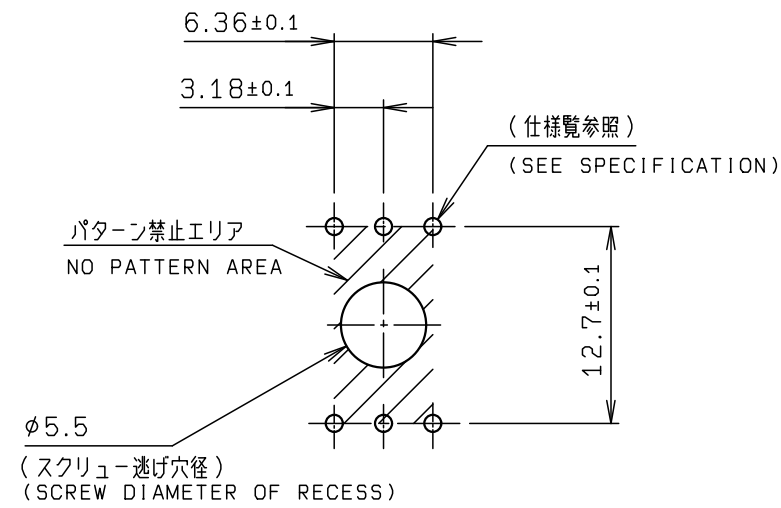
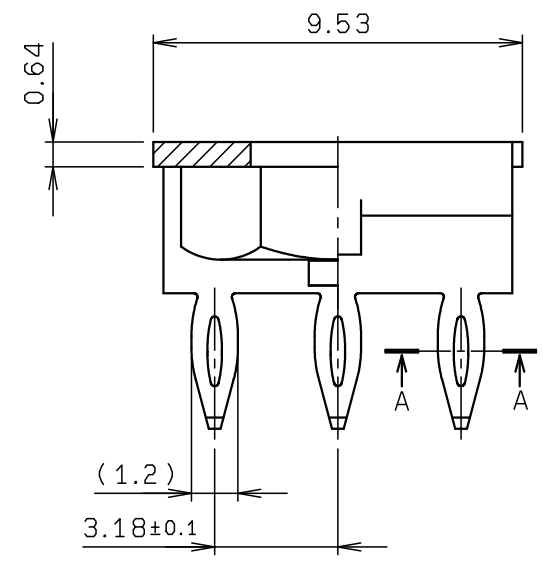


NO.	DESCRIPTION	PART NO.	QTY	MATERIAL	DRW NO.	REMARKS
1	POWER INSERT		1	COPPER ALLOY		UNDER COAT Ni: 1.25μmMIN. Sn-Cu 2μmMIN.
2	NUT		1	COPPER ALLOY		SPECIAL SCREW Ni PLATED



仕様 SPECIFICATION			
P/F仕様 P/F SPECIFICATION 適用基板 APPLICABLE BOARD	基板厚 BOARD THICKNESS	1.6MIN.	2.3MIN.
	下穴径 PREPARED HOLE DIAMETER	φ1.1±0.025	
	銅めっき厚 COPPER PLATED THICKNESS	25~65μm	25~50μm
	はんだめっき厚 SOLDER PLATED THICKNESS	—	7.6μmMIN.
	仕上げ径 FINISHED HOLE DIAMETER	φ1±0.05	φ1 ^{+0.05} _{-0.1}
DIP仕様 DIP SPECIFICATION 適用基板 APPLICABLE BOARD	仕上げ径 FINISHED HOLE DIAMETER	φ1.65±0.1	



推奨基板取付け寸法 (S=2:1)
RECOMMENDED MOUNTING DIMENSION

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ROHS規制対応
COMPLIANT WITH
ROHS REGULATIONS

TOLERANCE / 一般公差 (S)		PRODUCT SPEC / 製品規格		B	DCN19902	2019/09/02	M. YOSHIDA			K. YAMANE	
X < 10	±0.2			A	DCN-814	2003/08/07	K. KAIHARA	T. MORI	N. HAYASHI		
10 ≤ X < 30	±0.25	UNIT	ANGLE	O	EDN-468	2002/06/14	K. KAIHARA	T. MORI	S. HARADA		
30 ≤ X	±0.3	mm	3RD	NO.	EDN/DCN	DATE	ISSUE	CHECKED	APPROVED		
ANGLE / 角度	±3°	SCALE	DATE	PART NAME / 品名							
		5 : 1	2002/06/14	SERIES 9069							
DRAWN Y. OISHI				DESIGNED K. KAIHARA		CHECKED T. MORI		APPROVED S. HARADA		PART NO. / 型番 00 9069 9060 06 800	
				DWG NO. / 図番 BJS 9069007				SHEET / REV 1 / 1		B	

8 7 6 5 4 3 2 1